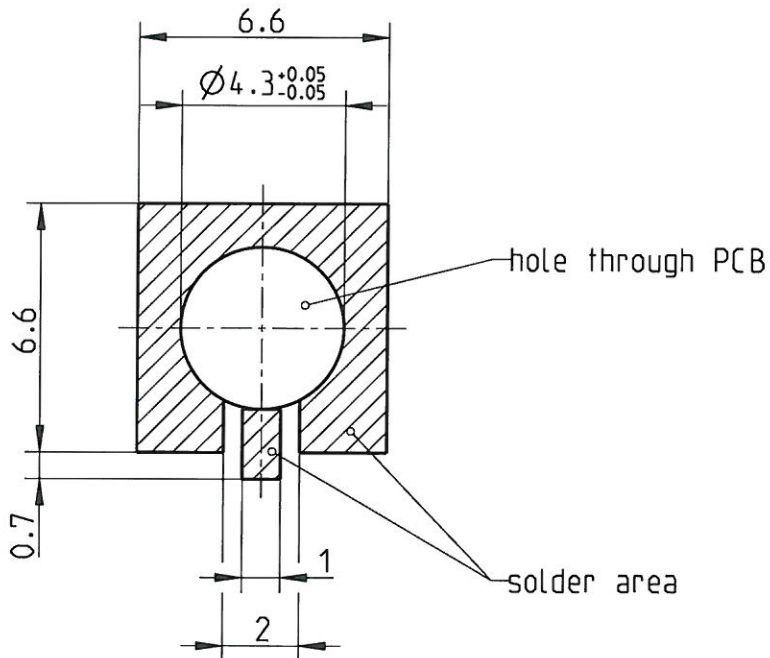


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Leiterplatten-Layout
PCB layout
B 121



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TCC_F8_05_PCB_Einzelteil
Prüf: I:\Pse-conf\Wagner
Datei: A:\ZUGL\TCC_F8_P8H
Ver. Nr.: 1.2

Dimensions in mm

ISO-Projektion Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 m-H		RN 006-01 dimensions <0,5 and symmetry		scale: 5:1 material:		weight(g): surface(mm ²):	
				date		name		title:			
				drawn 14.11.2005		A_Nobis		Leiterplatten-Layout PCB layout			
				check. 24.07.07		WZ					
				appr. 24.07.07		Krautwald					
				dimensioning incl. finish							
b00 07-0537 A_Nobis 23.07.2007 a00 05-0615 A_Nobis 15.11.2005				distribution to:		FE AZ QSM RMT .		drawing-no... MB_121		sheet: 1	
rev. change-no name date				X				remarks: .		of: 1	